



SOT616-9

HVQFN24, thermal enhanced very thin quad flat package, no leads, 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 0.85 mm body

25 May 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN24
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-01-2021
Manufacturer package code	98ASA01674D

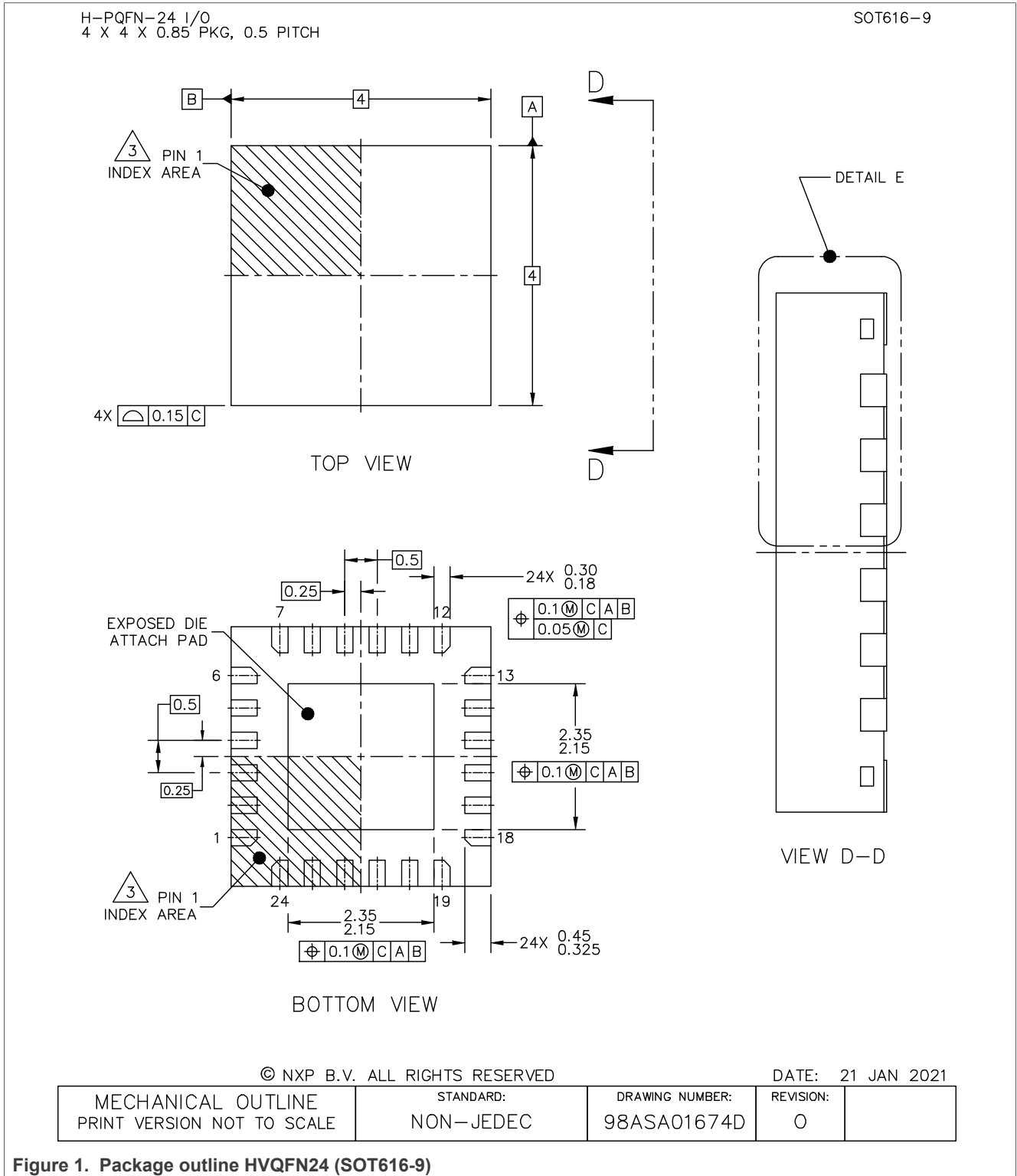
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.85	4	4.15	mm
package width	3.85	4	4.15	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	

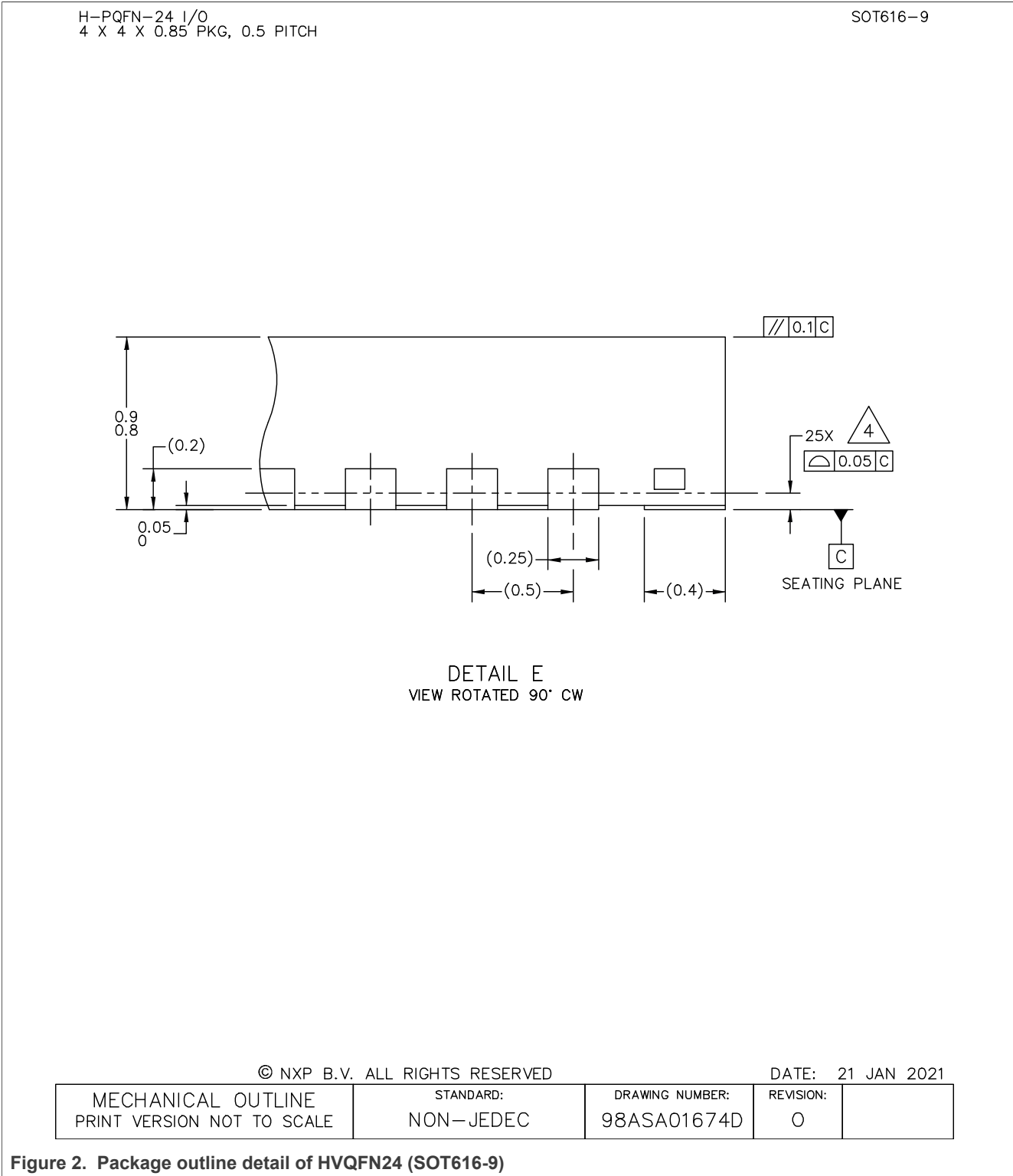


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2 Package outline

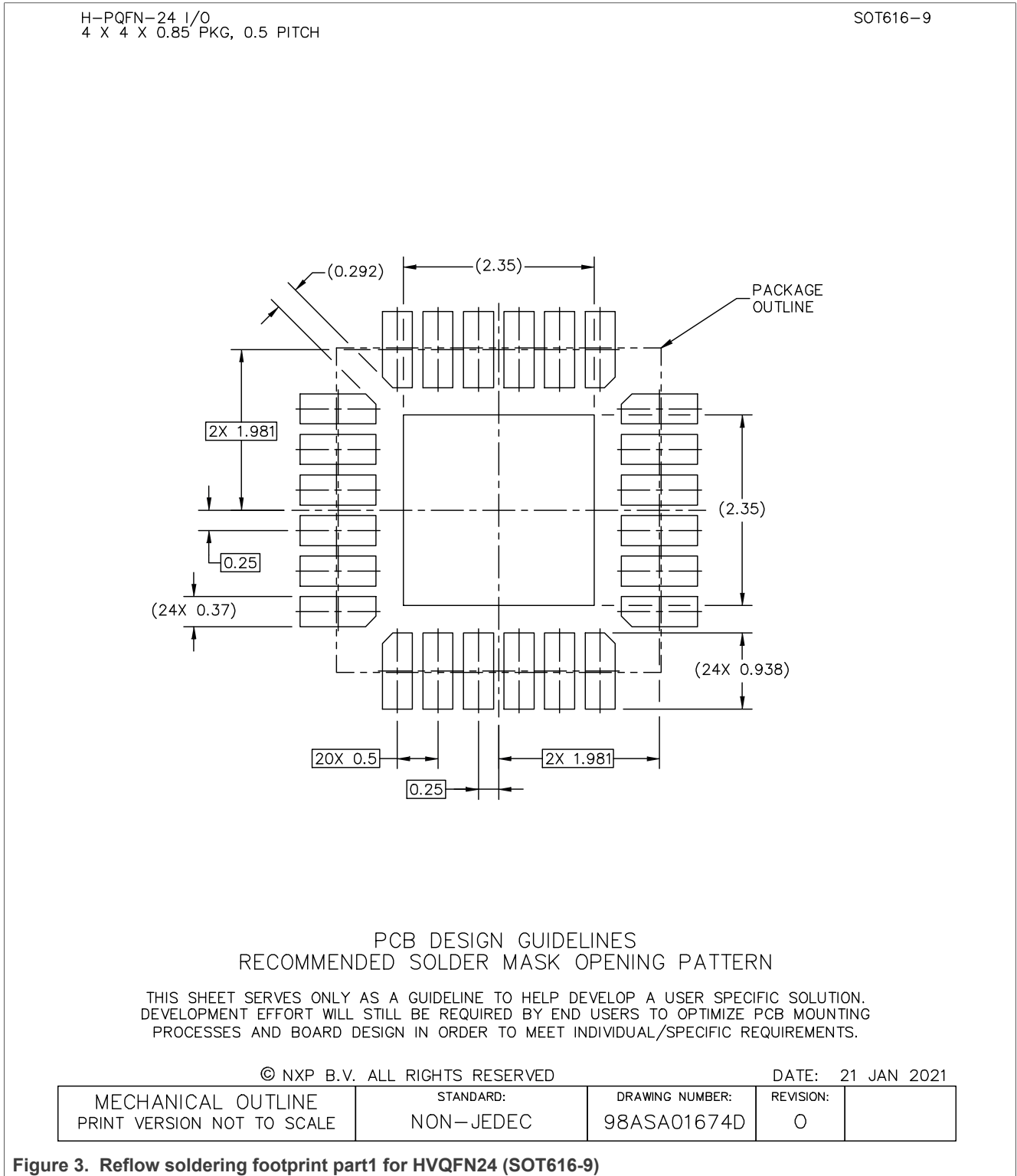


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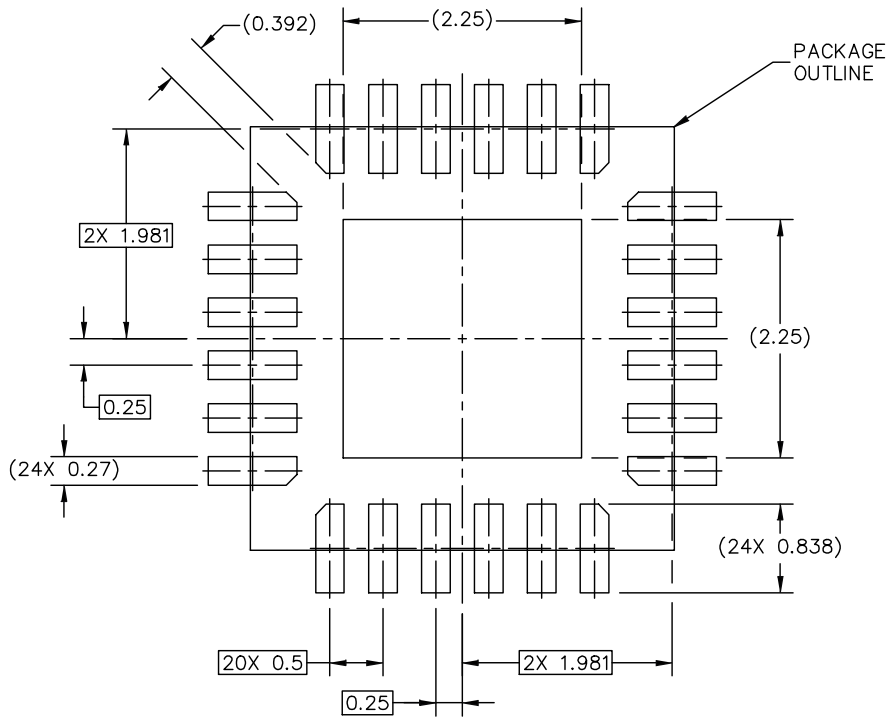
3 Soldering



HVQFN24, thermal enhanced very thin quad flat package, no leads, 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-24 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

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PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 4. Reflow soldering footprint part2 for HVQFN24 (SOT616-9)

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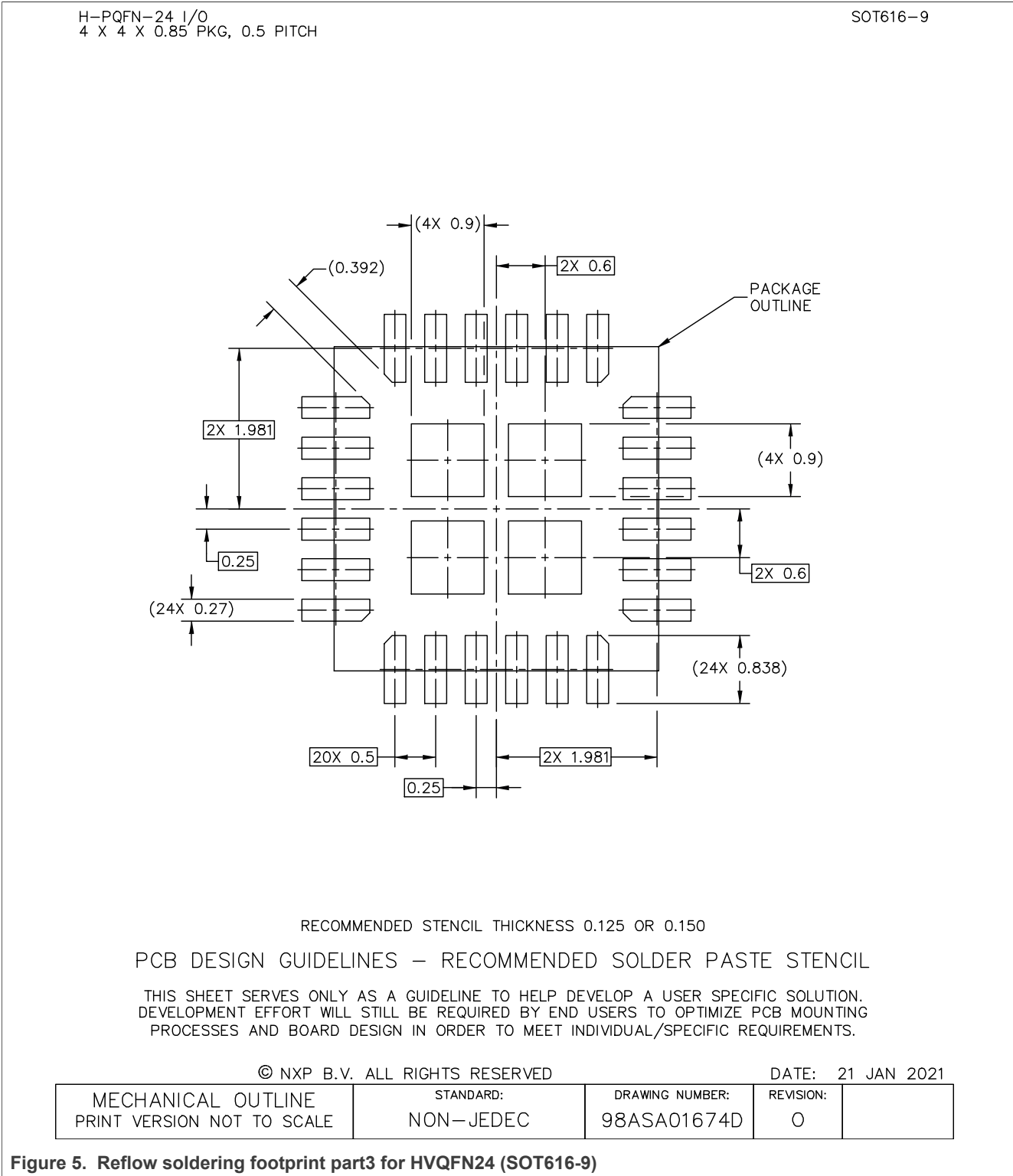


Figure 5. Reflow soldering footprint part3 for HVQFN24 (SOT616-9)

HVQFN24, thermal enhanced very thin quad flat package, no leads, 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 0.85 mm body

H-PQFN-24 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN24 (SOT616-9)

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4 Legal information

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